

NQS16LF BOM-style material declaration. BI Technologies Corporation

9/20/2010

No content here is banned per E.U. R.o.H.S.. Average mass of NQSLF thin film network is 0.08 grams each. Prepared by Eric Arnold (714) 447-2565
Weights in table above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification		
Die	substrate	7.29%	Al2O3	1344-28-1	0.006			
			CaO	1305-78-8	1.50E-06			
			FeO2	1345-25-1	3.00E-06			
			MgO	1309-48-4	1.50E-06			
			MnO2	1313-13-9	5.99E-06			
			SiO2, amorphous	7631-86-9	8.99E-06			
			TiO2	13463-67-7	3.00E-06			
			nichrome resistor	0.00013%	NiCrOx	combination of 7440-02-0, 7440-47-3, & 1308-38-9	1.07E-07	
			nickel barrier	0.0002%	Ni	7440-02-0	1.53E-07	
			gold conductor	0.004%	Au	7440-57-5	3.63E-06	
			BCB passivation	0.004%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	3.44E-06	
Leadframe	copper alloy	33.8%	Cu	7440-50-8	0.027			
			Fe	7439-89-6	6.53E-04			
			P	7723-14-0	8.33E-06			
			Zn	7440-66-6	3.33E-05			
			Sn	7440-31-5	0.001			
			Ag	7440-22-4	7.30E-04			
Die adhesive	conductive epoxy	0.9%	Ag	7440-22-4	5.60E-04			
			trade secret	unknown	1.40E-04	non-hazardous		
Wire bonds	gold	0.04%	Au	7440-57-5	3.34E-05			
Molding compound	filled epoxy	55.7%	carbon black	1333-86-4	2.29E-04			
			epoxy resin, cresol novolac	29690-82-2	9.15E-04			
			SiO2, fused silica	60676-86-0	0.040			
			trade secret	unknown	0.005	non-hazardous		
			trade secret	unknown	3.30E-05	non-hazardous		
Ink marking	epoxy	0.04%	trade secret	unknown	3.30E-05	non-hazardous		